

LISTING OF CLAIMS:

1. (Currently amended) A semiconductor device comprising:

a semiconductor chip, which produces heat when operated;

a heat conducting plate for conducting heat provided on one side of the semiconductor chip;

an insulating sheet, which is a dielectric and is compressively deformable, also provided on the one side of the semiconductor chip, wherein the heat conducting plate is positioned between the semiconductor chip and the insulating sheet, and the insulating sheet is secured to the heat conducting plate; and

a resin molding covering the semiconductor chip, the plate, and the sheet such that the sheet is exposed from the resin molding.
2. (Previously presented) The semiconductor device of claim 1, wherein the heat conductivity of the insulating sheet is greater than that of the resin molding.
3. (Previously presented) The semiconductor device of claim 2, wherein the insulating sheet is made of silicone rubber.
- 4-6 (Canceled)

7. (Previously presented) The semiconductor device of claim 1, wherein the insulating sheet is adhered to the heat conducting plate using a coating resin applied to the heat conducting plate.

8. (Original) The semiconductor device of claim 7, wherein the coating resin is polyamide resin.

9. (Previously presented) The semiconductor device of claim 1, wherein the semiconductor chip forms part of a stack, and the stack includes the plate, and opposite sides of the semiconductor chip are soldered to members of the stack.

10-16 (Canceled)

17. (New) The semiconductor device of claim 1, wherein the insulating sheet is made of a dielectric resin material.